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Multi-Chip Module With Extension

Abstract of the Disclosure

A multi-chip module may include a pair of chips which are arranged one over the other on each side of a laminate layer. A central passage through the laminate layer provides a passage to wire bond a chip on a first side of the laminate layer to contacts on a second side of the laminate layer. A second chip is also placed on the second side of the laminate layer. By causing the laminate layer to extend outwardly beyond the first and second chips, and providing contacts on the extension, contact may be made to the laminate layer extension for electrically coupling the first and second chips to the outside world.

Figure 1